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LRDIMM System-Level Validation Results on Future Intel® Xeon® Processor E5 Family

Listed below are the results from a small sample of DDR3 LRDIMMs tested on future Intel® Xeon® processor E5 family . We are providing this information as a guide to module compatibility with Intel server reference platforms. This testing is not intended to replace the normal OEM qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

Updated / New Part

The configurations validated only for the same supplier and same part number across memory channels

LRDIMM DDR3L-1066 Quad Rank 3DIMM Per Channel / 3Slot Per Channel / 4Channel

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Crucial	CT102472BL1339Q.36FMA5D	8GB	9	B	Micron	MT41K256M8DA-125:M	2Gb	x8	1129	Inphi	GS02A	
Crucial	CT204872BL1339Q.36DMA5D	16GB	9	C	Micron	MT41K1G4THV-125:M	2Gb	x4	1130	Inphi	GS02A	1
Hynix	HMT42GL7BMR4A-H9	16GB	9	C	Hynix	H5TC4G43BMR-H9A	2Gb	x4	1140	Inphi	GS02A	1
Micron	MT36KSZF1G72LDZ-1G4M1A5	8GB	9	B	Micron	MT41K256M8DA-125:M	2Gb	x8	1129	Inphi	GS02A	
Micron	MT72KSZS2G72LZ-1G4M1A5	16GB	9	C	Micron	MT41K1G4THV-125:M	2Gb	x4	1130	Inphi	GS02A	1
Samsung	M386B2K70DM0-YH90	16GB	9	C	Samsung	K4B4G0446D-MYH9	2Gb	x4	1124	Inphi	GS02A	1
Samsung	M386B4G70BM0-YH90	32GB	9	C	Samsung	K4B8G0446B-MYH9	4Gb	x4	1122	Inphi	GS02A	1

1 - DDP (Dual-Die Package)

LRDIMM DDR3-1066 Quad Rank 3DIMM Per Channel / 3Slot Per Channel / 4Channel

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Crucial	CT102472BL1339Q.36FMA5D	8GB	9	B	Micron	MT41K256M8DA-125:M	2Gb	x8	1129	Inphi	GS02A	
Crucial	CT204872BL1339Q.36DMA5D	16GB	9	C	Micron	MT41K1G4THV-125:M	2Gb	x4	1130	Inphi	GS02A	1
Hynix	HMT42GL7BMR4A-H9	16GB	9	C	Hynix	H5TC4G43BMR-H9A	2Gb	x4	1140	Inphi	GS02A	1
Elpida	EBJ34LH4B3RA-DJ-F	32GB	9	K	Elpida	EDJ8404B3MA-DJ-F	4Gb	x4	1105	Inphi	GS02A	1
Micron	MT36KSZF1G72LDZ-1G4M1A5	8GB	9	B	Micron	MT41K256M8DA-125:M	2Gb	x8	1129	Inphi	GS02A	
Micron	MT72KSZS2G72LZ-1G4M1A5	16GB	9	C	Micron	MT41K1G4THV-125:M	2Gb	x4	1130	Inphi	GS02A	1
Samsung	M386B2K70DM0-YH90	16GB	9	C	Samsung	K4B4G0446D-MYH9	2Gb	x4	1124	Inphi	GS02A	1
Samsung	M386B4G70BM0-YH90	32GB	9	C	Samsung	K4B8G0446B-MYH9	4Gb	x4	1122	Inphi	GS02A	1

1 - DDP (Dual-Die Package)

LRDIMM DDR3-1333 Quad Rank 2DIMM Per Channel / 3Slot Per Channel / 4Channel

DIMM					DRAM						Register		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Elpida	EBJ34LH4B3RA-DJ-F	32GB	9	K	Elpida	EDJ8404B3MA-DJ-F	4Gb	x4	1105	Inphi	GS02A	1
Samsung	M386B2K70DM0-YH90	16GB	9	C	Samsung	K4B4G0446D-MYH9	2Gb	x4	1124	Inphi	GS02A	1
Samsung	M386B4G70BM0-YH90	32GB	9	C	Samsung	K4B8G0446B-MYH9	4Gb	x4	1122	Inphi	GS02A	1

1 - DDP (Dual-Die Package)

Updated on December 14, 2011

Approved Test Labs:

The following test labs have the capability of performing the DDR3 LRDIMM system-level testing. For further information please contact:

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